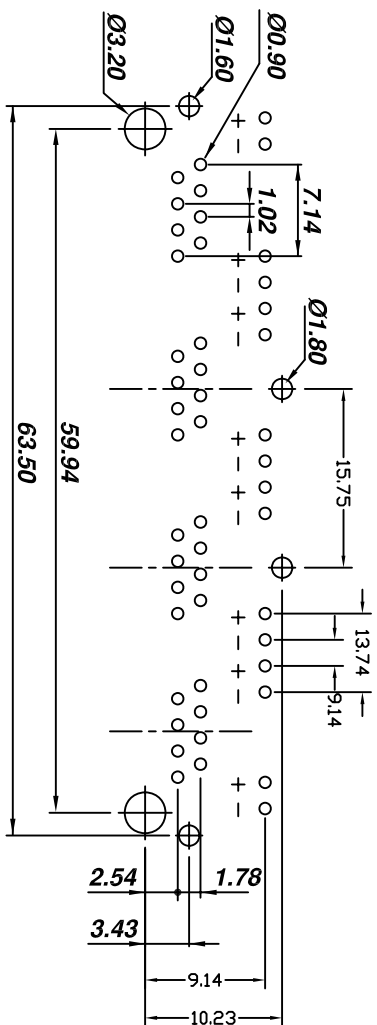
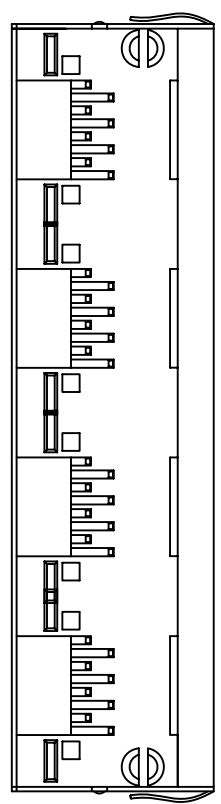
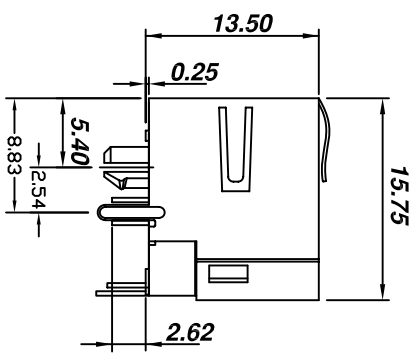
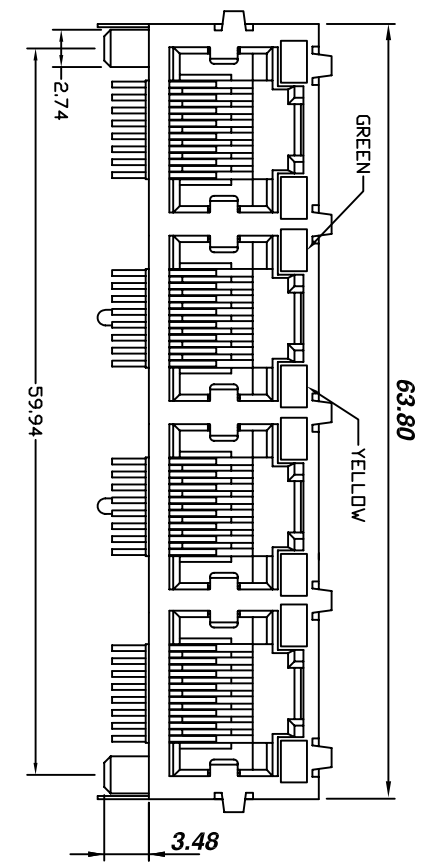


Rev	AWO #	Description	Date	Appr
X		Released	8/14/03	

APPROVED: \_\_\_\_\_  
 DATE: \_\_\_\_\_ TITLE: \_\_\_\_\_



**PCB LAYOUT**

**SPECIFICATION:**

**Material:** Polybutylene Terephthalate (PBT), glass-reinforced thermoplastic rated UL 94V-0  
**Contacts and Shield:** Copper Alloy

**Plating:** "X" min gold to MIL-G-45204, Type II, Grade C on contact area over 50 µin min nickel underplate to QQ-N-290, Grade C, tin-lead on solder tails.

**Electrical:**  
 Operation voltage: 150 VAC max  
 Current rating: 1 Amp max  
 Contact resistance: 20 mohm max  
 Insulation resistance: 500 Mohm min @ 100 VDC between adjacent contacts

**Environmental:**  
 Dielectric withstanding voltage: 1000 VAC/minute between shield and contacts.  
 1500 VAC/minute between shield and contacts.  
 Operating temperature: -40°C to +70°C

**CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F**  
 Lead free, RoHS compliant.  
 Recommended soldering temp: 235°C for 5 sec.

"X"	PLATING
0	15 µin Gold
1	30 µin Gold
2	50 µin Gold



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE MM [INCHES] TOLERANCES: EXCEPT AS NOTED INCHES	
.X	± .10
.XX	± .020
.XXX	± .015
.XXX	± .010
APPROVALS	DATE
DRAWN	SLS
CHECKED	
APPROVED	

**ADAM TECH**  
 909 Rahway Avenue, Union, NJ 07083  
 Phone: 908-687-5000 Fax: 908-687-0214

TITLE: MODULAR TELEPHONE JACK, R/A  
 W/ PANEL GROUNDS, LED GRN/YEL

SIZE: X  
 PART NO.: MTJG-4-88ARX1-FSM-PG-LH  
 SCALE: NTS  
 SHEET 1 OF 1